

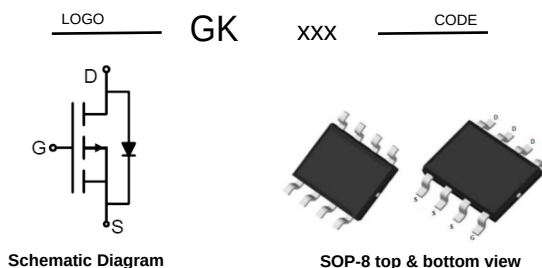
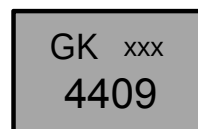
Features

Low Gate Charge
100% UIS Tested, 100% DVDS Tested
High Power and current handing capability
Lead free product is acquired

V_{DS} -30 V
 I_D -18 A
 $R_{DS(ON)}$ 5.8m Ω

Application

PWM Applications
Load Switch
Power Management



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings

Symbol	Parameter	Limit	Unit
V_{DS}	Drain-Source Voltage ($V_{GS}=0V$)	-30	V
V_{GS}	Gate-Source Voltage ($V_{DS}=0V$)	± 20	V
I_D	Drain Current-Continuous($T_A=25^{\circ}C$)	-18	A
	Drain Current-Continuous($T_A=100^{\circ}C$)	-14	A
I_{DM} (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	-88	A
P_D	Maximum Power Dissipation($T_A=25^{\circ}C$)	5.2	W
	Maximum Power Dissipation($T_A=100^{\circ}C$)	2.1	W
E_{AS}	Avalanche energy (Note 2)	380	mJ
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 150	$^{\circ}C$

Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		24	$^{\circ}C/W$

Electrical Characteristics (T_J=25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =-250μA	-30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-30V, V _{GS} =0V T _J =25 °C			-1	μA
		V _{DS} =-30V, V _{GS} =0V T _J =125 °C			-100	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-1		-2.2	V
g _{FS}	Forward Transconductance	V _{DS} =-5V, I _D =-10A		45		S
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =-10V, I _D =-20A T _J =25 °C		5.8	7.8	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =-4.5V, I _D =-20A T _J =25 °C		8	11	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =-15V,V _{GS} =0V, f=1.0MHz		4994		pF
C _{oss}	Output Capacitance			410		pF
C _{rss}	Reverse Transfer Capacitance			221		pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1.0MHz		8		Ω
Switching Parameters						
t _{d(on)}	Turn-on Delay Time	V _{GS} =-10V, V _{DS} =-30V, R _L =2Ω, R _{GEN} =3Ω		13		nS
t _r	Turn-on Rise Time			115		nS
t _{d(off)}	Turn-Off Delay Time			78		nS
t _f	Turn-Off Fall Time			86		nS
Q _g	Total Gate Charge	V _{GS} =-10V, V _{DS} =-15V, I _D =-20A		40.9		nC
Q _{gs}	Gate-Source Charge			9.9		nC
Q _{gd}	Gate-Drain Charge			14.3		nC
Source-Drain Diode Characteristics						
I _{SD}	Source-Drain Current (Body Diode)				-18	A
V _{SD}	Forward on Voltage ^(Note 3)	V _{GS} =0V, I _S =-10A			-1.2	V
t _{rr}	Reverse Recovery Time	I _F =-10A, dI/dt=-100A/μs		13		ns
Q _{rr}	Reverse Recovery Charge	I _F =-10A, dI/dt=-100A/μs		8		nC

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

Notes 2.EAS condition: T_J=25°C, V_{DD}=-30V, V_G=-10V, R_g=25Ω, L=0.5mH.

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.

RATING AND CHARACTERISTIC CURVES

Figure 1. Output Characteristics

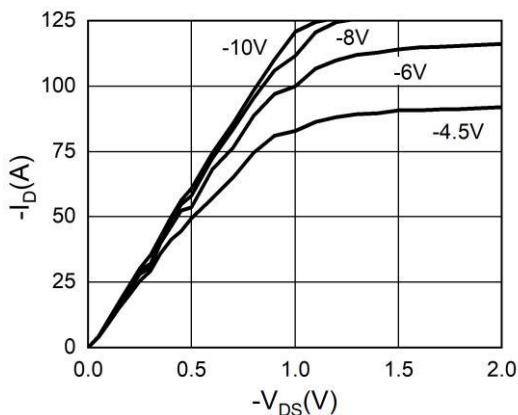


Figure 2. Transfer Characteristics

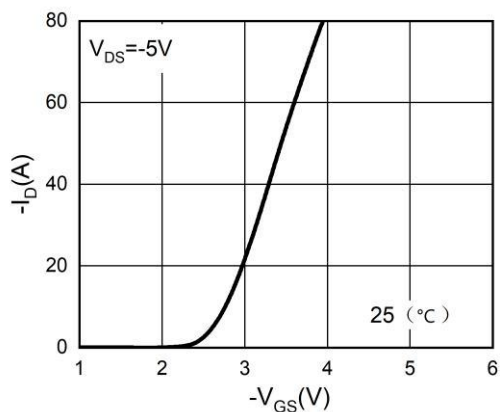


Figure 3. Power Dissipation

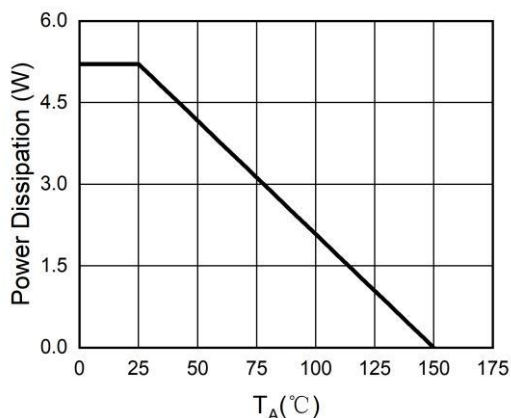


Figure 4. Drain Current

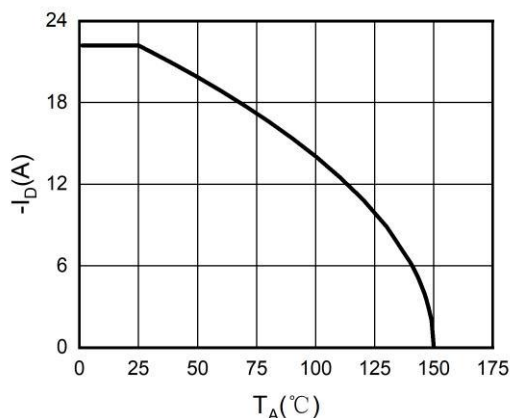


Figure 5. BV_{DSS} vs Junction Temperature

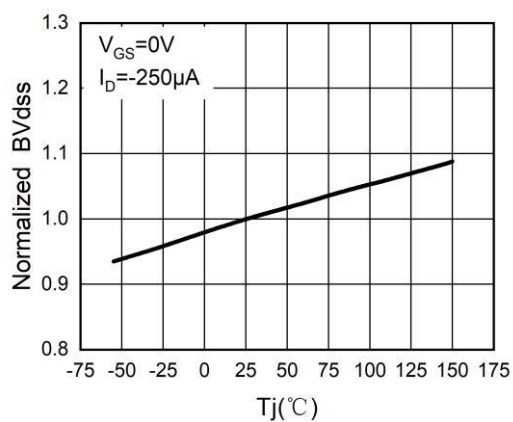
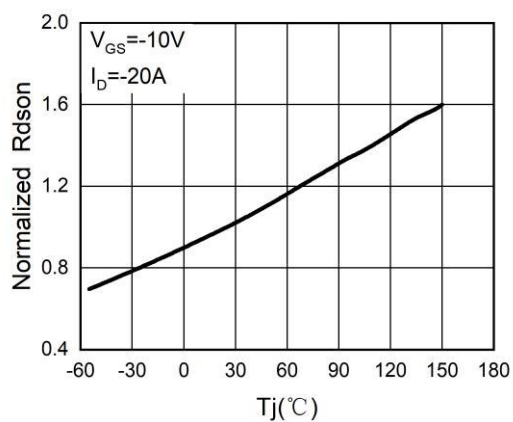


Figure 6. $R_{DS(ON)}$ vs Junction Temperature



RATING AND CHARACTERISTIC CURVES

Figure 7. Gate Charge Waveforms

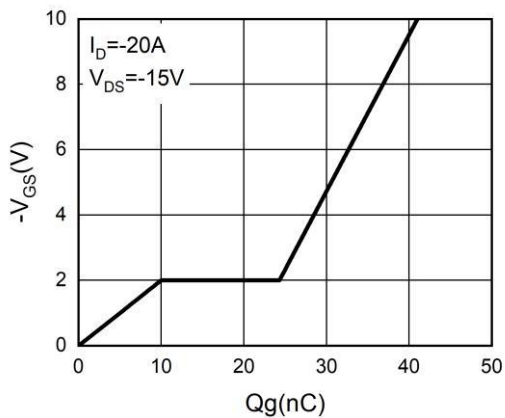


Figure 8. Capacitance

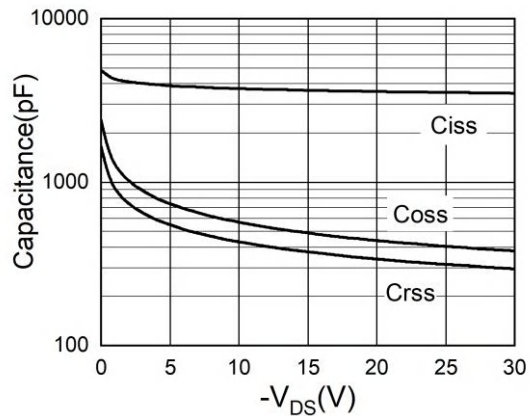


Figure 9. Body-Diode Characteristics

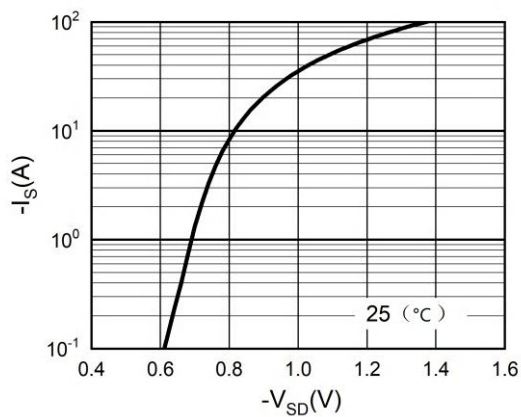
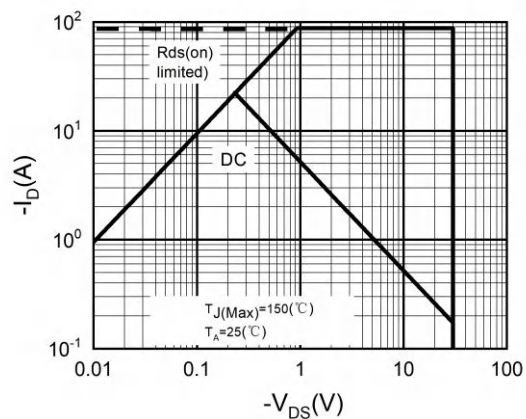
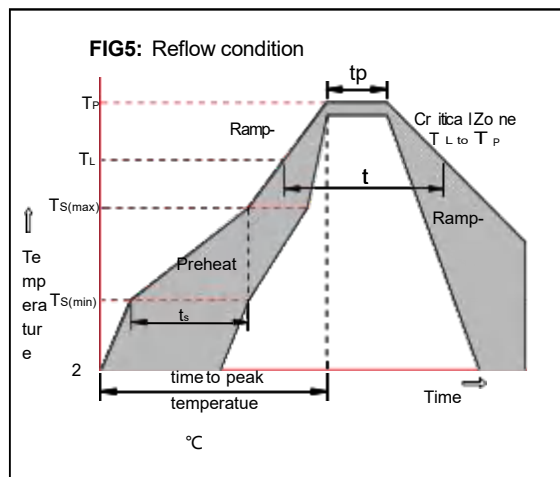


Figure 10. Maximum Safe Operating Area



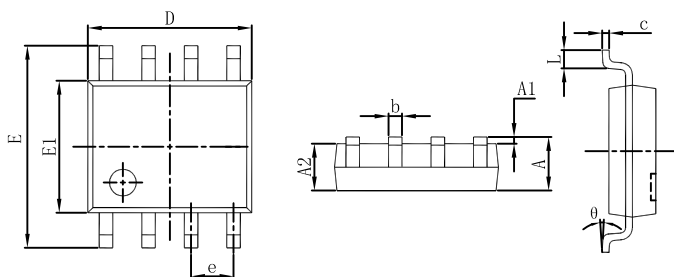
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150 °C
	-Temperature Max($T_{s(max)}$)	+200 °C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3 °C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3 °C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217 °C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5) °C
Time within 5 °C of actual Peak Temp (t_P)		30 secs. Max
Ramp-down Rate		6 °C/sec. Max
Time 25 °C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260 °C

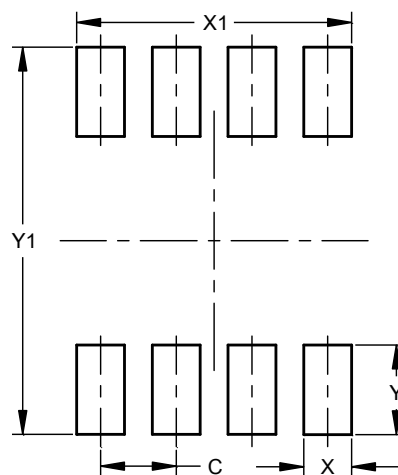


Package Dimensions & Suggested Pad Layout

SOP-8

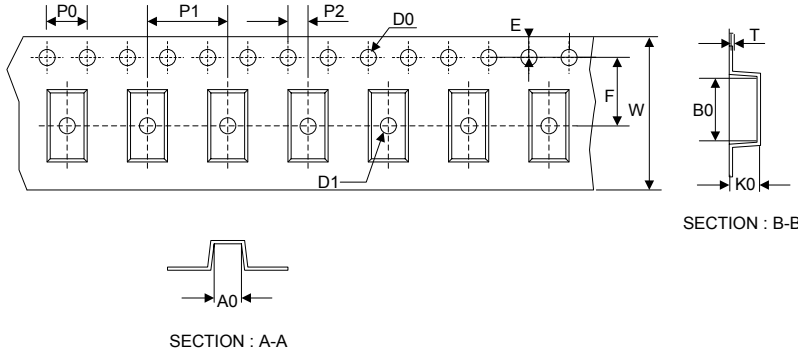
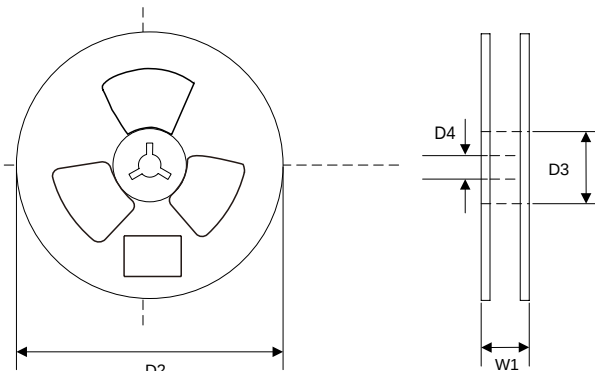
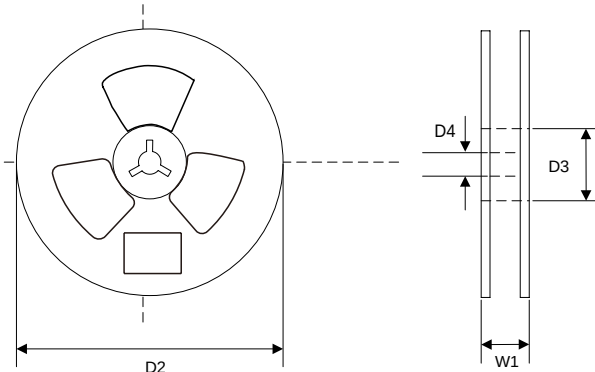


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270 (BSC)		0.050 (BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°



Dimensions	Value (in mm)
C	1.27
X	0.70
X1	4.51
Y	2.00
Y1	7.00

Tape & reel specification

Tape		Symbol	Dimension (mm)
		P0	4.00±0.20
		P1	8.00±0.20
		P2	2.00±0.20
		D0	1.55±0.20
		D1	1.55±0.20
		E	1.75±0.15
		F	5.50±0.20
		W	12.00±0.20
		A0	7.00±0.20
		B0	5.70±0.20
		K0	1.35±0.20
		T	0.23±0.20
13" Reel		D2	330.0±5.0
		D3	73Min.
		D4	13.5±2.5
		W1	16.0±3.0
		Quantity: 3000PCS	
13" Reel		D2	330.0±5.0
		D3	73Min.
		D4	13.5±2.5
		W1	16.0±3.0
		Quantity: 4000PCS	